



Material Content Data Sheet



Sales Product Name		IPD50N10S3L-16		Issued		29. August 2013		
MA#		MA000389822						
Package		PG-TO252-3-11		Weight*		372.00 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.429	1.19	1.19	11906	11906
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		630	
	inorganic material	phosphorus	7723-14-0	0.070	0.02		189	
	non noble metal	copper	7440-50-8	234.187	62.95	63.03	629531	630350
wire	non noble metal	aluminium	7429-90-5	3.859	1.04	1.04	10373	10373
encapsulation	organic material	carbon black	1333-86-4	1.220	0.33		3279	
	plastics	epoxy resin	-	21.348	5.74		57386	
	inorganic material	silicondioxide	60676-86-0	99.419	26.73	32.80	267254	327919
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10054	10054
plating	non noble metal	nickel	7440-02-0	0.091	0.02		244	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	245
solder	noble metal	silver	7440-22-4	0.085	0.02		229	
	non noble metal	tin	7440-31-5	0.068	0.02		183	
	non noble metal	lead	7439-92-1	3.252	0.87	0.91	8741	9153
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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